



**DISCO**

Kiru · Kezuru · Migaku Technologies



# Electroformed Bond Hub Blades **ZHRF SERIES**

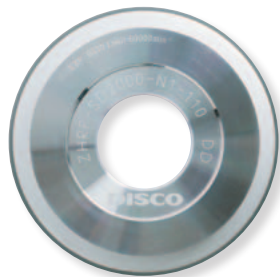
## High blade strength to prevent slant and wavy cutting



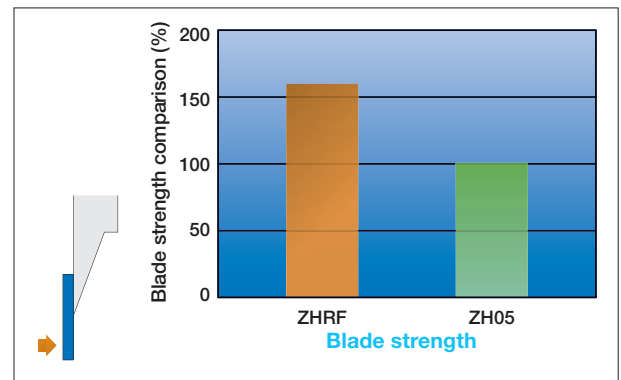
### The ZHRF Series provides stable quality even in high load processing, due to improved blade strength.

By employing new technologies, the blade strength is further improved compared to previous hub blades. The ZHRF minimizes blade slant cutting even under high load conditions such as for high speed processing, thick wafer cutting or wafers that have a lot metal on the streets. It also achieves a stable processing result. In addition, by combining a ZHRF blade with laser grooving for the processing of low dielectric constant (Low-k) layer wafers, backside chipping and peeling are eliminated and high speed processing is possible.

- Shows stable processing performance in high load processing.
- Realizes high speed wafer cutting after laser grooving.
- Supports processing required for long blade exposure.



### ■ Blade strength comparison



Compared to the previous Series, the ZHRF Series is seen to have improved strength.

### Applications

*Silicon wafers, etc.*

